

Date: - 22 March, 2011

Data Sheet Issue:- A1

Advance Data

High Power Sonic FRD

Type E4000TC25C

Absolute Maximum Ratings

	VOLTAGE RATINGS	MAXIMUM LIMITS	UNITS
V_{RRM}	Repetitive peak reverse voltage, (note 1)	2500	V
V_{RSM}	Non-repetitive peak reverse voltage, (note 1)	2600	V
$V_{R(d.c.)}$	Maximum reverse d.c. voltage (note 1)	1500	V

	OTHER RATINGS (note 6)	MAXIMUM LIMITS	UNITS
$I_{F(AV)M}$	Mean forward current, T _{sink} =55°C, (note 2)	4080	Α
$I_{F(AV)M}$	Mean forward current. T _{sink} =100°C, (note 2)	2630	Α
$I_{F(AV)M}$	Mean forward current. T _{sink} =100°C, (note 3)	1572	Α
I _{F(RMS)}	Nominal RMS forward current, T _{sink} =25°C, (note 2)	7662	Α
I _{F(d.c.)}	D.C. forward current, T _{sink} =25°C, (note 4)	6557	Α
I _{FSM}	Peak non-repetitive surge t _p =10ms, V _{RM} =50%V _{RRM} , (note 5)	50	kA
I _{FSM2}	Peak non-repetitive surge t _p =10ms, V _{RM} ≤10V, (note-5)	55	kA
l ² t	I ² t capacity for fusing t _p =10ms, V _{RM} =60%V _{RRM} , (note 5)	12.5×10 ⁻⁶	A ² s
l ² t	I^2 t capacity for fusing $t_p=10$ ms, $V_{RM}\leq 10$ V, (note-5)	15.1×10 ⁻⁶	A^2s
P _{rr}	Maximum non-repetitive peak reverse recovery power, (note 7)	15	MW
T _{j op}	Operating temperature range	-40 to +150	°C
T_{stg}	Storage temperature range	-40 to +150	°C

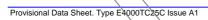
Notes:

- 1) De-rating factor of 0.13% per °C is applicable for T_i below 25°C.
- 2) Double side cooled, single phase; 50Hz, 180° half-sinewave.
- 3) Single side cooled, single phase; 50Hz, 180 half-sinewave.
- 4) Double side cooled.
- 5) Half-sinewave, 150°C Tinitial
- 6) Current (I_F) ratings have been calculated using V_{T0} and r_T (see page 2)
- 7) T_j=T_{jop}, I_F=2250Å, di/dt=2500A/us V_f=1250V and L_s=200nH. Test circuit and sample waveform are shown in diagram 1. IGBT type T2250AB25E used as switch.

Characteristics

	PARAMETER	MIN.	TYP.	MAX.	TEST CONDITIONS (Note 1)	UNITS
\/	Maximum peak forward voltage	-	1.87	2.0	I _{FM} =4000A	V
V_{FM}		-	-	2.66	I _{FM} =8000A	, v
V_{T0}	Threshold voltage	-	-	1.406	Current range 4080 A - 12240A (Note 2)	X
r _T	Slope resistance	-	-	0.149	Current range 4000 A - 12240A (Note 2)	Ω m Ω
V _{T01}	Threshold voltage	-	-	1.4	Current range 4000A 4200A	(\mathcal{Y})
r _{T1}	Slope resistance	-	-	0.15	Current range 4000A - 12000A	mΩ
\ /	Maximum farward recovery yeltage	-	-	50	di/dt = 3000A/µs	\bigcup_{V}
V_{FRM}	Maximum forward recovery voltage	-	-	25	di/dt = 3000A/µs, T _j =25°C	/ v
	Book roverse surrent	-	-	100	Rated V _{RRM}	mA
I _{RRM}	Peak reverse current	-	-	10	Rated V _{RRM} , T _j =25°C	IIIA
Q _{rr}	Recovered charge	-	6700	7400		μC
Q_{ra}	Recovered charge, 50% Chord	-	3100	-	I_{FM} =4000Å, t_p =1ms, di/dt=3500Å/ μ s, V_r =1250V, 50% and L_s =200nH. IGBT type	μC
I _{rm}	Reverse recovery current	-	2480	2700	T2250AB25E used as switch. (note 3)	Α
t _{rr}	Reverse recovery time, 50% Chord	-	2.5	-		μs
D	The second resistance is unation to be established	-	-	0.008	Double side cooled	K/W
R_{thJK}	Thermal resistance, junction to heatsink	-	-	0.016	Single side cooled	K/W
F	Mounting force	60	-	75 ((Note 4)	kN
W_t	Weight	-	1.23	- \		kg

- Unless otherwise indicated T_j=150°C.
 V_{T0} and r_T were used to calculate the current ratings illustrated on page one.
 Figures 3-7 were compiled using these conditions. Test circuit and sample waveform are shown in diagram 1.
- 4) For clamp forces outside these limits, please consult factory.



Additional information on Ratings and Characteristics

1.0 De-rating Factor

A blocking voltage de-rating factor of 0.13% per °C is applicable to this device for T_j below 25°C.

2.0 ABCD Constants

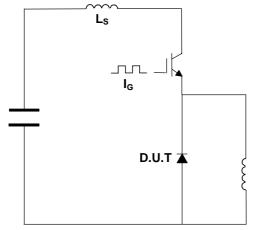
These constants (applicable only over current range of V_F characteristic in Figure 1) are the coefficients of the expression for the forward characteristic given below:

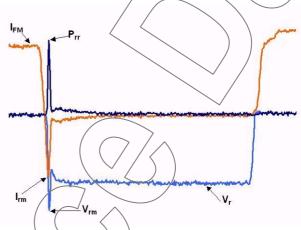
$$V_F = A + B \cdot \ln(I_F) + C \cdot I_F + D \cdot \sqrt{I_F}$$

where I_F = instantaneous forward current.

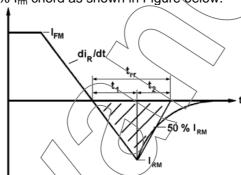
3.0 Reverse recovery ratings

Diagram 1 – Reverse Recovery test circuit and sample waveform

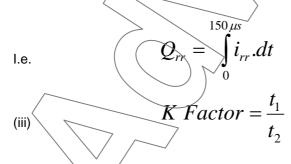




(i) Q_{ra} is based on 50% I_{rm} chord as shown in Figure below.



(ii) Q_{rr} is based on a 150μs integration time.



4.0 Reverse Recovery Loss

The following procedure is recommended for use where it is necessary to include reverse recovery loss.

From waveforms of recovery current obtained from a high frequency shunt (see Note 1) and reverse voltage present during recovery, an instantaneous reverse recovery loss waveform must be constructed. Let the area under this waveform be E joules per pulse. A new sink temperature can then be evaluated from:

$$T_{SINK} = T_{J(MAX)} - E \cdot \left[k + f \cdot R_{th(J-Hs)}\right]$$

Where $k = 0.2314 \, (^{\circ}C/W)/s$

E = Area under reverse loss waveform per pulse in joules (W.s.)

f = Rated frequency in Hz at the original sink temperature.

 $R_{th(J-Hs)} = d.c.$ thermal resistance (°C/W)

The total dissipation is now given by:

$$W_{(tot)} = W_{(original)} + E \cdot f$$

NOTE 1 - Reverse Recovery Loss by Measurement

This device has a low reverse recovered charge and peak reverse recovery current. When measuring the charge, care must be taken to ensure that:

- (a) AC coupled devices such as current transformers are not affected by prior passage of high amplitude forward current.
- (b) A suitable, polarised, clipping circuit must be connected to the input of the measuring oscilloscope to avoid overloading the internal amplifiers by the relatively high amplitude forward current signal.
- (c) Measurement of reverse recovery waveform should be carried out with an appropriate critically damped snubber, connected across diode anode to cathode. The formula used for the calculation of this snubber is shown below:

$$R^2 = 4 \cdot \frac{V_r}{C_s \cdot di/dt}$$

Where: V_r = Commutating source voltage

C_S = Snubber capacitance

R = Snubber resistance

5.0 Computer Modelling Parameters

5.1 Device Dissipation Calculations

$$I_{AV} = \frac{-V_{T0} + \sqrt{V_{T0}^{2} + 4 \cdot ff^{2} \cdot r_{T} \cdot W_{AV}}}{2 \cdot ff^{2} \cdot r_{T}}$$

Where $V_{T0} = 1.406V$, $r_T = 0.149 \text{m}\Omega$

ff = form factor (normally unity for fast diode applications)

$$W_{AV} = \frac{\Delta T}{R_{th}}$$

$$\Delta T = T_{i(MAX)} - T_K$$

5.2 Calculation of V_F using ABCD Coefficients

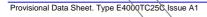
The forward characteristic I_F Vs V_F, on page 6 is represented in two ways;

- the well established V_{T0} and r_T tangent used for rating purposes and a set of constants A, B, C, and D forming the coefficients of the representative equation for V_F in (ii) terms of I_F given below:

$$V_F = A + B \cdot \ln(I_F) + C \cdot I_F + D \cdot \sqrt{V_F}$$

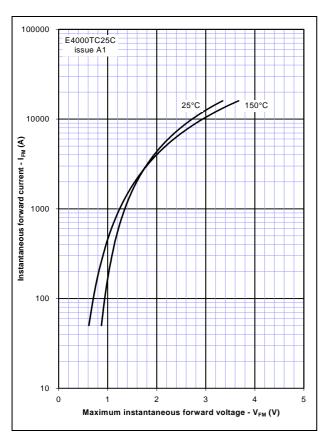
The constants, derived by curve fitting software, are given in this report for both hot and cold characteristics. The resulting values for V_F agree with the true device characteristic over a current range, which is limited to that plotted.

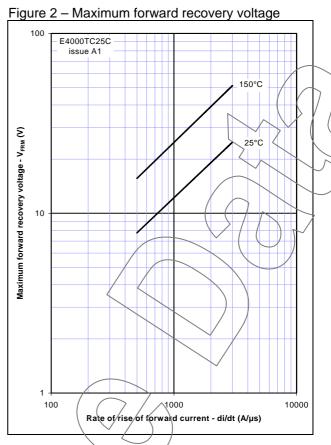
	25°C Coefficients	150°C Coefficients
Α	0.6303658	0.2906166
В	3.745470×10 ⁻²	5.054005×10 ⁻²
С	4.279123×10 ⁻⁵	3.953989×10 ⁻⁵
D	1.319665×10 ⁻²	1.785807×10 ⁻²

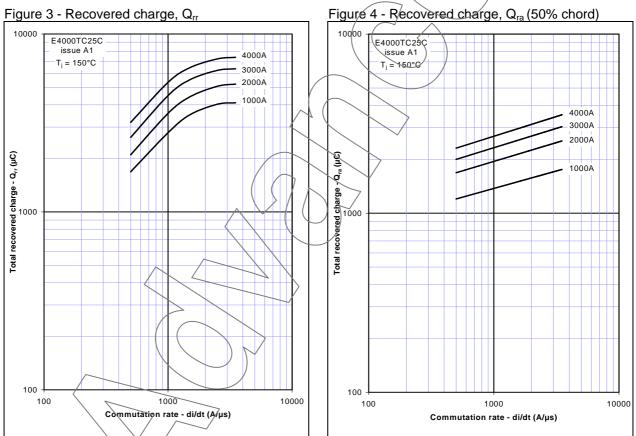


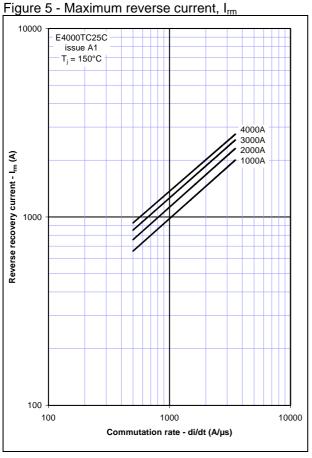
Curves

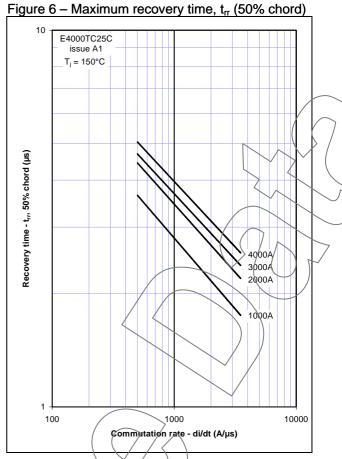
Figure 1 – Forward characteristics of limit device

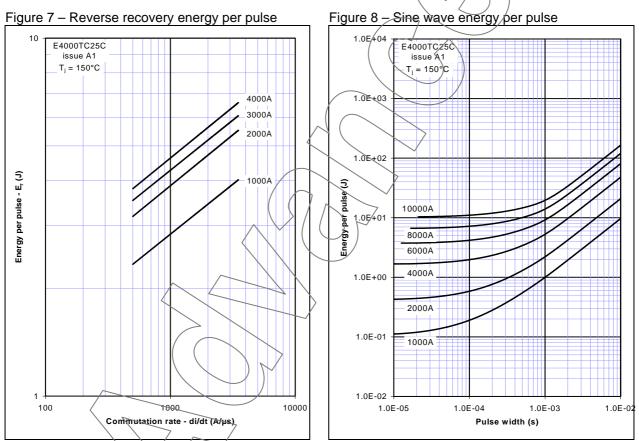


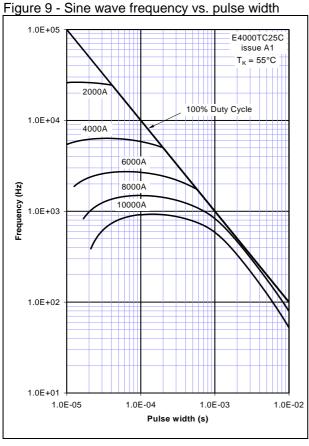


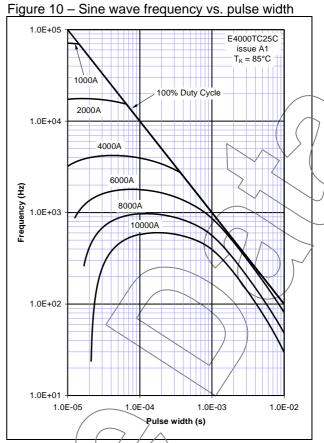












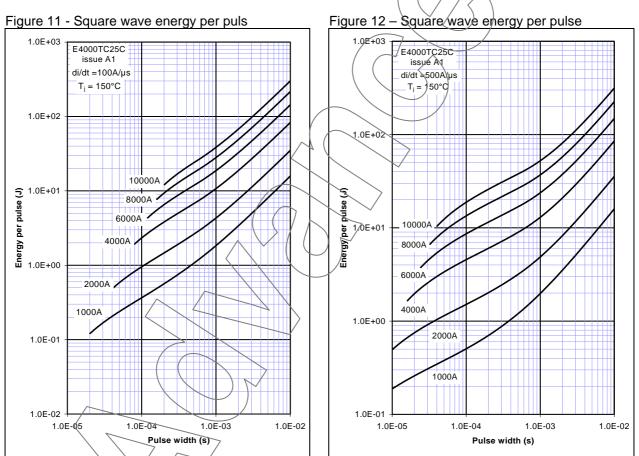


Figure 13 - Square wave frequency vs pulse width

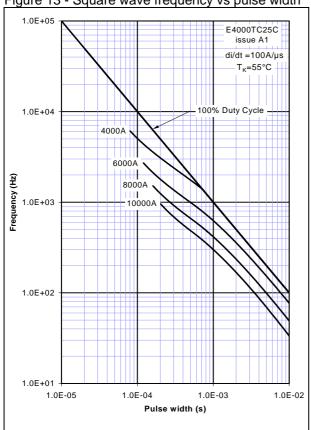


Figure 14 – Square wave frequency vs pulse width

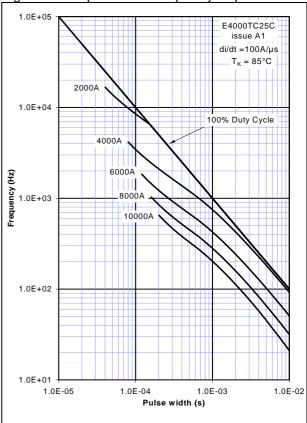


Figure 15 - Square wave frequency vs pulse width

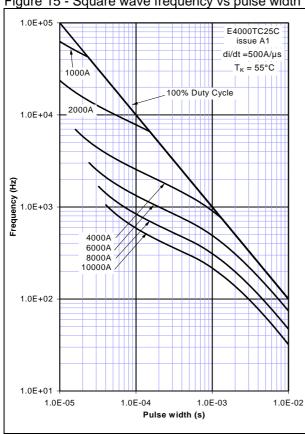


Figure 16 – Square wave frequency vs pulse width

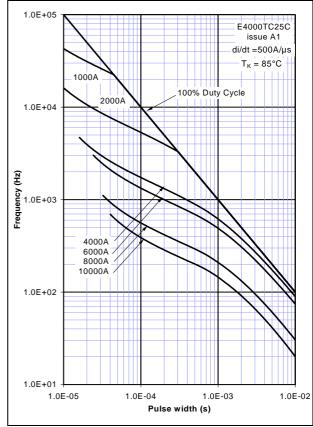
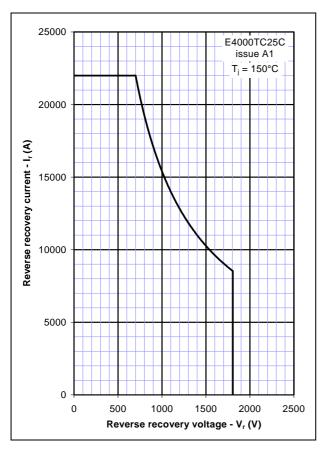
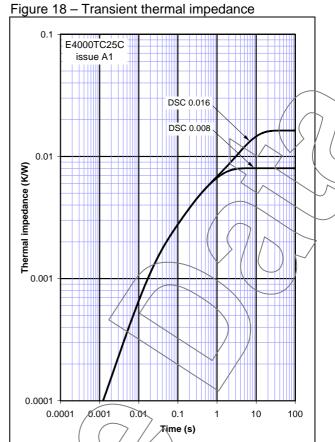
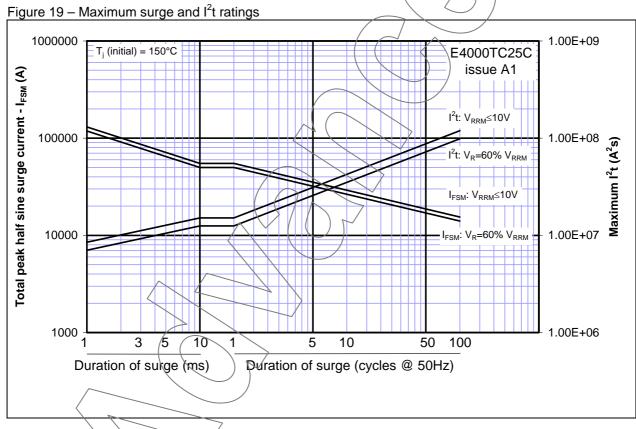


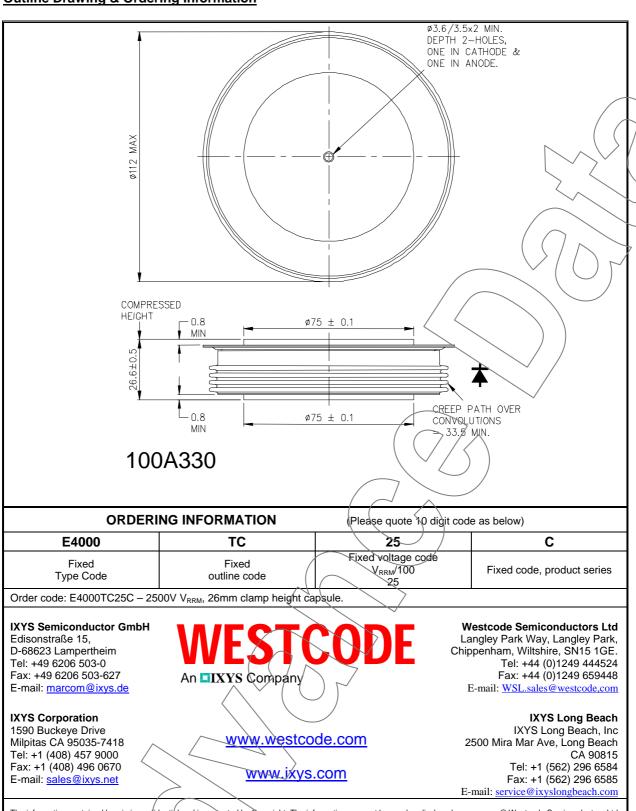
Figure 17 – Safe operating area







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